Minutes from OpenPICs WP 4 meeting 24-07-2017

Present: Longfei, Rob, Rui, Huub

Discussion/action points

Nr.	Description	Responsible
1.	Al-MQW	
	The design is delayed by another 2 weeks. It would be helpful to discuss with	Weiming,
	Peter (Smart) to see if their model can be used to get an initial numbers of	
	the composition and strain.	
	The Al-Q will be calibrated in both Nanolab and Smart reactors.	Longfei
2.	Zn diffusion tests	
	• SIMS measurement results just arrived. Looks very similar to CV results,	Rene
	except at 475C: max Zn concentration in InP is twice higher for SIMS than	
	CV, indicating the presence of Zn interstitials. More analysis underway.	
	A sample covered with a mask containing various opening transmissions	Longfei
	have been fabricated by Longfei. it will be used to obtain the dependence of	
	diffusion rate on mask patterns.	
	Get an empirical model based on more data points with MPW layerstack.	
3.	BCB planarization	
	Adhesion test of metal on BCB: tape test failed due to the poor adhesion of	Tjibbe
	BCB to native oxide on silicon (less than that of metal to BCB). Next test with	
	BCB on silicon oxide will be done soon.	
	Planarization test has been done on the sample from Smart. Tencor is back	
	from supplier, needs to be set up and calibrated.	
	Lithography parameters have to be re-optimized for BCB.	
4.	Stepper process	5.1
	The stabilization time for Stepper is determined experimentally as 24h.	Robert
	Test with MaN resist: we need some initial results in July, and samples to be	
	measured with X-SEM by an internship student in August.	
	Overlay test using Scanner patterned samples is planned with Jeroen.	
5.	Etching process	D:
	• The new CH4-H2 recipe (optimized for ~3 degree side-wall angle in Smart's	Rui
	ICP) will be transferred to Nanolab after a few more fine-tuning.	Longfei
	New test for the Cl2-CH4-H2 recipe has been delayed due to the breakdown of Scapper Longfei will plan new runs with Pohert and Jorgen	LUIIBIEI
-	of Scanner. Longfei will plan new runs with Robert and Jeroen.	
6.	Planning Lincoming due dates for milestones:	
	 Upcoming due dates for milestones: M 6.1 (end of August) Process developed for AZ and MaN based lithography. 	Robert
	M 4.1 (end of September) BCB insulation and metal plating tested: ready for	Tjibbe
	joint MPW validation	TIDDE
	A project review meeting (first-year) has been scheduled on 29 August.	Weiming
	More details of the agenda will follow.	** Cilling
	 Longfei will leave as of September 1. We are contacting people to take over 	Longfei
	this part of work. He is writing documents for the hand-over.	_30.0.
	this part of work. He is writing documents for the hand-over.	

Next meeting: 13:30-15:00, 21-8-2017, Flux 10.177